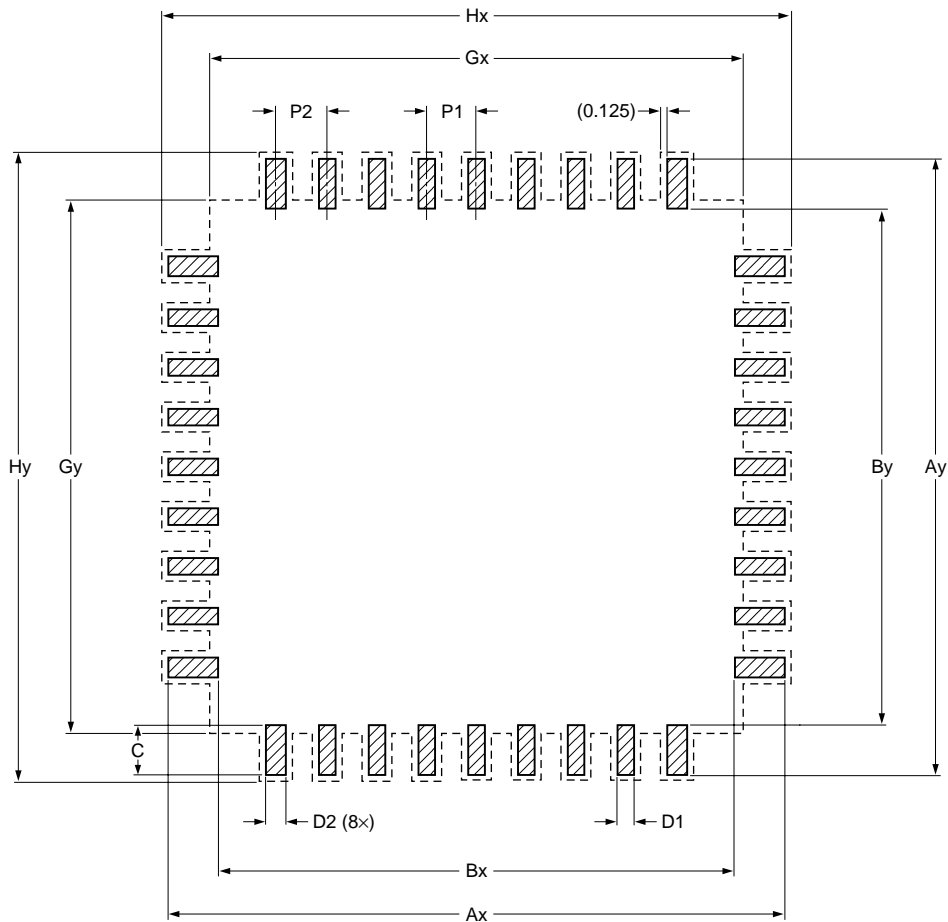



Footprint information for reflow soldering of LQFP32 package

SOT358-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
 ---- occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.800	0.850	9.700	9.700	7.300	7.300	1.200	0.500	0.600	7.500	7.500	9.950	9.950